

300 mA 10 V Input LDO Regulator for Automotive Applications

No. EC-205-231025

OUTLINE

The RP170x is an LDO regulator featuring 300 mA output current. Having the 10 V maximum input voltage, the RP170x can be used in 2 cell lithium-ion battery powered portable appliances and besides a portable equipment. The supply current is Typ. 23 μ A though an excellent response characteristics. The output voltage range from 1.2 V is possible. The output voltage accuracy and temperature-drift coefficient of output voltage of the RP170x is excellent. RP170x has a fold-back protection circuit and a thermal shutdown circuit. Moreover, a standby mode with ultra low supply current can be realized with the chip enable function. SOT-23-5 and SOT-89-5 with high power dissipation packages are available.

FEATURES

- Input Voltage Range (Maximum Rating).....2.6 V to 10.0 V (12 V)
- Operating Temperature-40° C to 105°C (RP170xx1x-xx-AE)
-40° C to 125°C (RP170xx1x-xx-KE)
- Supply CurrentTyp. 23 μ A
- Standby Current.....Typ. 0.1 μ A
- Dropout VoltageTyp. 0.20 V (I_{OUT} = 100 mA, V_{OUT} = 3.0 V)
.....Typ. 0.77 V (I_{OUT} = 300 mA, V_{OUT} = 2.8 V)
- Ripple RejectionTyp. 70 dB (f = 1 kHz)
- Temperature-Drift Coefficient of Output Voltage ...Typ. $\pm$ 80 ppm/°C
- Line RegulationTyp. 0.02%/V
- Output Voltage Accuracy..... $\pm$ 1.0%
- PackagesSOT-23-5, SOT-89-5
- Output Voltage Range.....1.2 V/1.25 V/1.5 V/1.8 V/2.5 V/2.8 V/2.9 V/3.0 V/
3.3 V/4.2 V /5.0 V /5.5 V/6.0 V
*Contact Ricoh sales representatives for other voltages.
- Built-in Fold Back Protection CircuitTyp. 40 mA (Current at short mode)
- Built-in Thermal Shutdown Circuit.....Shutdown Temperature at 165°C
- Constant Slope Circuit (Soft-start Function)
- Ceramic capacitors are recommended to be used with this IC 1.0 μ F or more

APPLICATIONS

- Power source for accessories such as car audios, car navigation systems, and ETC systems
- Power source for ECUs such as EV inverter and battery charge control unit

SELECTION GUIDE

The output voltage, auto discharge function⁽¹⁾, and package for the ICs can be selected at the user's request.

Selection Guide

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
RP170Nxx1*-TR-#E	SOT-23-5	3,000 pcs	Yes	Yes
RP170Hxx1*-T1-#E	SOT-89-5	1,000 pcs	Yes	Yes

xx: Specify the set output voltage (V_{SET})

1.2 V (12) / 1.25 V (12) / 1.5 V (15) / 1.8 V (18) / 2.5 V (25) / 2.8 V (28) / 2.9 V (29) / 3.0 V (30) /
3.3 V (33) / 4.2 V (42) / 5.0 V (50) / 5.5 V (55) / 6.0 V (60)

If the output voltage includes the 3rd digit, indicate the digit of 0.01 as follows.

1.25 V → RP170x121*5

* : The auto discharge functions at off state are as follows.

(B) without auto discharge function at off state

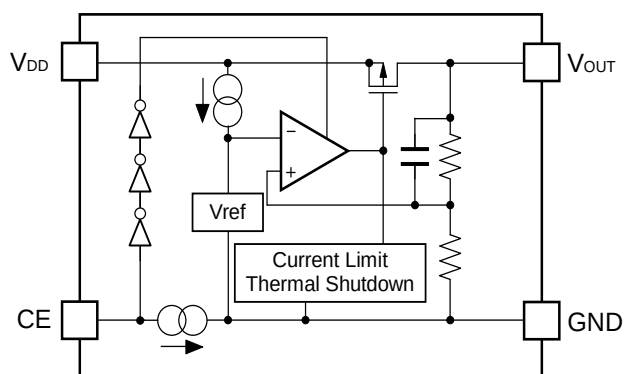
(D) with auto discharge function at off state

#: Quality Class

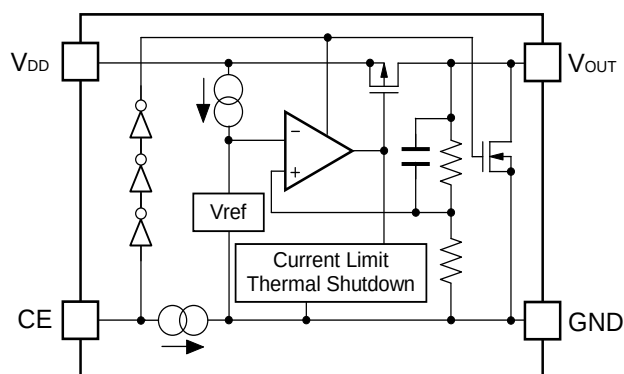
#	Operating Temperature Range	Test Temperature
A	-40°C to 105°C	25°C, High
K	-40°C to 125°C	Low, 25°C, High

⁽¹⁾ Auto-discharge function quickly lowers the output voltage to 0 V by releasing the electrical charge accumulated in the external capacitor when the chip enable signal is switched from the active mode to the standby mode.

BLOCK DIAGRAMS

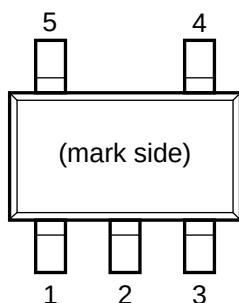


RP170xxxxB Block Diagram

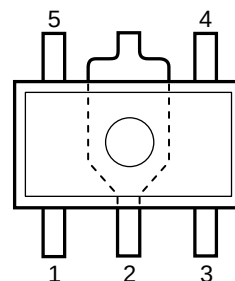


RP170xxxxD Block Diagram

PIN DESCRIPTIONS



SOT-23-5 Pin Configuration



SOT-89-5 Pin Configuration

SOT-23-5 Pin Description

Pin No	Symbol	Pin Description
1	V_{DD}	Input Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin (Active-high)
4	NC	No Connection
5	V_{OUT}	Output Pin

SOT-89-5 Pin Description

Pin No	Symbol	Pin Description
1	V_{OUT}	Output Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin (Active-high)
4	NC	No Connection
5	V_{DD}	Input Pin

ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings

Symbol	Item			Rating	Unit
V_{IN}	Input Voltage			12	V
V_{CE}	Input Voltage (CE Pin)			12	V
V_{OUT}	Output Voltage			-0.3 to $V_{IN} + 0.3$	V
I_{OUT}	Output Current			330	mA
P_D	Power Dissipation ⁽¹⁾	SOT-23-5	JEDEC STD. 51-7 Test Land Pattern	830	mW
		SOT-89-5	JEDEC STD. 51-7 Test Land Pattern	3200	
T_j	Junction Temperature			-40 to 150	°C
T_{stg}	Storage Temperature Range			-55 to 150	°C

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS

Recommended Operating Conditions

Symbol	Item			Rating	Unit
V_{IN}	Input Voltage			2.6 to 10	V
T_a	Operating Temperature Range	RP170xx1x-xx-AE		-40 to 105	°C
		RP170xx1x-xx-KE		-40 to 125	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

⁽¹⁾ Refer to *POWER DISSIPATION* for detailed information.

ELECTRICAL CHARACTERISTICS

$V_{IN} = V_{SET} + 1\text{ V}$, $I_{OUT} = 1\text{ mA}$, unless otherwise noted.

The specifications surrounded by are guaranteed by design engineering at $-40^{\circ}\text{C} \leq T_a \leq 105^{\circ}\text{C}$.

RP170xxxB/D (-AE) Electrical Characteristics

($T_a = 25^{\circ}\text{C}$)

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V_{OUT}	Output Voltage	$1.5\text{ V} < V_{SET}$	$T_a = 25^{\circ}\text{C}$	$V_{SET} \times 0.99$	$V_{SET} \times 1.01$	V
			$-40^{\circ}\text{C} \leq T_a \leq 105^{\circ}\text{C}$	$V_{SET} \times 0.965$	$V_{SET} \times 1.03$	
		$V_{SET} \leq 1.5\text{ V}$	$T_a = 25^{\circ}\text{C}$	-15	15	mV
			$-40^{\circ}\text{C} \leq T_a \leq 105^{\circ}\text{C}$	-53	45	
I_{OUT}	Output Current		300			mA
$\Delta V_{OUT} / \Delta I_{OUT}$	Load Regulation	$0.1\text{ mA} \leq I_{OUT} \leq 300\text{ mA}$		10	80	mV
V_{DIF}	Dropout Voltage	$I_{OUT} = 300\text{ mA}$	Refer to the <i>Product-specific Electrical Characteristics</i>			
I_{SS}	Supply Current	$I_{OUT} = 0\text{ mA}$		23	45	μA
$I_{standby}$	Standby Current	$V_{IN} = 10.0\text{ V}$ $V_{CE} = \text{GND}$		0.1	1.2	μA
$\Delta V_{OUT} / \Delta V_{IN}$	Line Regulation	$V_{SET} + 0.5\text{ V} \leq V_{IN} \leq 10.0\text{ V}$ (Incase that $V_{SET} \leq 2.1\text{ V}$, $2.6\text{ V} \leq V_{IN} \leq 10.0\text{ V}$)		± 0.02	± 0.25	%/V
I_{SC}	Short Current Limit	$V_{OUT} = 0\text{ V}$		40		mA
I_{PD}	CE Pull-down Current			0.30		μA
V_{CEH}	CE Input Voltage "H"		1.7			V
V_{CEL}	CE Input Voltage "L"				0.8	V
T_{TSD}	Thermal Shutdown Temperature	Junction Temperature		165		$^{\circ}\text{C}$
T_{TSR}	Thermal Shutdown Released Temperature	Junction Temperature		110		$^{\circ}\text{C}$
R_{LOW}	Nch On Resistance for Auto Discharge (RP170xxx1D only)	$V_{CE} = 0\text{ V}$ $V_{IN} = 7.0\text{ V}$		250		Ω

All test items listed under Electrical Characteristics are done under the pulse load condition ($T_j \approx T_a = 25^{\circ}\text{C}$).

ELECTRICAL CHARACTERISTICS (continued)

Product-specific Electrical Characteristics

The specifications surrounded by are guaranteed by design engineering at $-40^{\circ}\text{C} \leq T_a \leq 105^{\circ}\text{C}$.

RP170xxxB/D (-AE)

($T_a = 25^{\circ}\text{C}$)

Product Name	V_{OUT} [V] ($T_a = 25^{\circ}\text{C}$)			V_{OUT} [V] ($T_a = -40$ to 105°C)			V_{DIF} [V]	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	TYP.	MAX.
RP170x121x	1.185	1.200	1.215	1.147	1.200	1.245	1.400	1.925
RP170x121x5	1.235	1.250	1.265	1.197	1.25	1.295		
RP170x151x	1.485	1.500	1.515	1.447	1.500	1.545	1.200	1.655
RP170x181x	1.782	1.800	1.818	1.737	1.800	1.854	0.980	1.305
RP170x251x	2.475	2.500	2.525	2.413	2.500	2.575	0.770	1.185
RP170x281x	2.772	2.800	2.828	2.702	2.800	2.884		
RP170x291x	2.871	2.900	2.929	2.799	2.900	2.987		
RP170x301x	2.970	3.000	3.030	2.895	3.000	3.090	0.600	0.995
RP170x331x	3.267	3.300	3.333	3.185	3.300	3.399		
RP170x421x	4.158	4.200	4.242	4.053	4.200	4.326	0.500	0.875
RP170x501x	4.950	5.000	5.050	4.825	5.000	5.150		
RP170x551x	5.445	5.500	5.555	5.308	5.500	5.665		
RP170x601x	5.940	6.000	6.060	5.790	6.000	6.180		

ELECTRICAL CHARACTERISTICS (continued)

$V_{IN} = V_{SET} + 1\text{ V}$, $I_{OUT} = 1\text{ mA}$, unless otherwise noted.

RP170xxxxB/D (-KE) Electrical Characteristics

($-40^{\circ}\text{C} \leq T_a \leq 125^{\circ}\text{C}$)

Symbol	Item	Conditions		Min.	Typ.	Max.	Unit
V_{OUT}	Output Voltage	$1.5\text{ V} < V_{SET}$	$T_a = 25^{\circ}\text{C}$	$V_{SET} \times 0.99$		$V_{SET} \times 1.01$	V
			$-40^{\circ}\text{C} \leq T_a \leq 125^{\circ}\text{C}$	$V_{SET} \times 0.960$		$V_{SET} \times 1.035$	
		$V_{SET} \leq 1.5\text{ V}$	$T_a = 25^{\circ}\text{C}$	-15		15	mV
			$-40^{\circ}\text{C} \leq T_a \leq 125^{\circ}\text{C}$	-60		50	
I_{OUT}	Output Current			300			mA
$\Delta V_{OUT} / \Delta I_{OUT}$	Load Regulation	$0.1\text{ mA} \leq I_{OUT} \leq 300\text{ mA}$			10	85	mV
V_{DIF}	Dropout Voltage	$I_{OUT} = 300\text{ mA}$		Refer to the <i>Product-specific Electrical Characteristics</i>			
I_{SS}	Supply Current	$I_{OUT} = 0\text{ mA}$			23	47	μA
$I_{standby}$	Standby Current	$V_{IN} = 10.0\text{ V}$ $V_{CE} = \text{GND}$			0.1	1.25	μA
$\Delta V_{OUT} / \Delta V_{IN}$	Line Regulation	$V_{SET} + 0.5\text{ V} \leq V_{IN} \leq 10.0\text{ V}$ (In case that $V_{SET} \leq 2.1\text{ V}$, $2.6\text{ V} \leq V_{IN} \leq 10.0\text{ V}$)			± 0.02	± 0.25	%/V
I_{SC}	Short Current Limit	$V_{OUT} = 0\text{ V}$			40		mA
I_{PD}	CE Pull-down Current				0.30		μA
V_{CEH}	CE Input Voltage "H"			1.7			V
V_{CEL}	CE Input Voltage "L"					0.8	V
T_{TSD}	Thermal Shutdown Temperature	Junction Temperature			165		$^{\circ}\text{C}$
T_{TSR}	Thermal Shutdown Released Temperature	Junction Temperature			110		$^{\circ}\text{C}$
R_{LOW}	Nch On Resistance for Auto Discharge (RP170xxx1D only)	$V_{CE} = 0\text{ V}$ $V_{IN} = 7.0\text{ V}$			250		Ω

ELECTRICAL CHARACTERISTICS (continued)

Product-specific Electrical Characteristics

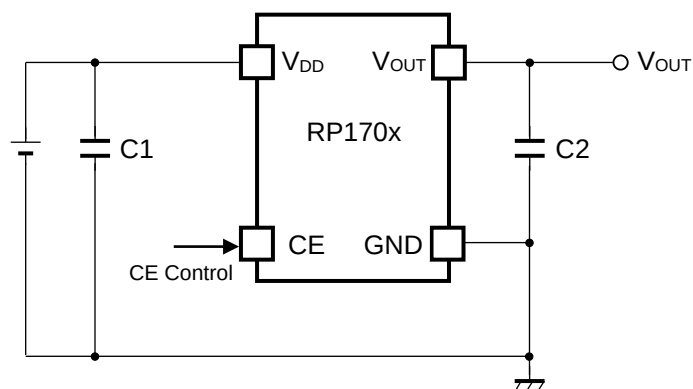
RP170xxxB/D (-KE)

(-40°C ≤ Ta ≤ 125°C)

Product Name	V _{OUT} [V] (Ta = 25°C)			V _{OUT} [V] (Ta = -40 to 125°C)			V _{DIF} [V]	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	TYP.	MAX.
RP170x121x	1.185	1.200	1.215	1.140	1.200	1.250	1.400	1.925
RP170x121x5	1.235	1.250	1.265	1.190	1.250	1.300		
RP170x151x	1.485	1.500	1.515	1.440	1.500	1.550	1.200	1.655
RP170x181x	1.782	1.800	1.818	1.728	1.800	1.863	0.980	1.305
RP170x251x	2.475	2.500	2.525	2.400	2.500	2.587	0.770	1.185
RP170x281x	2.772	2.800	2.828	2.688	2.800	2.898		
RP170x291x	2.871	2.900	2.929	2.784	2.900	3.001		
RP170x301x	2.970	3.000	3.030	2.880	3.000	3.105	0.600	0.995
RP170x331x	3.267	3.300	3.333	3.168	3.300	3.415		
RP170x421x	4.158	4.200	4.242	4.032	4.200	4.347	0.500	0.875
RP170x501x	4.950	5.000	5.050	4.800	5.000	5.175		
RP170x551x	5.445	5.500	5.555	5.280	5.500	5.692		
RP170x601x	5.940	6.000	6.060	5.760	6.000	6.210		

APPLICATION INFORMATION

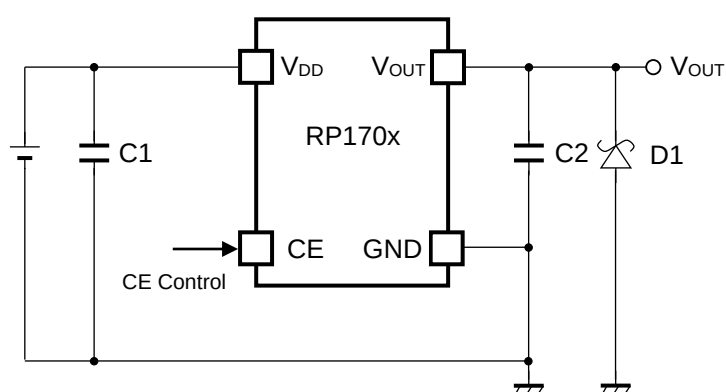
TYPICAL APPLICATION



External Components

Symbol	Descriptions
C1	1.0 μ F, Ceramic Capacitor, MURATA, GRM155B31A105KE15
C2	1.0 μ F, Ceramic Capacitor, MURATA, GRM155B31A105KE15

TYPICAL APPLICATION FOR IC CHIP BREAKDOWN PREVENTION



When a sudden surge of electrical current travels along the VOUT pin and GND due to a short-circuit, electrical resonance of a circuit involving an output capacitor (C2) and a short circuit inductor generates a negative voltage and may damage the device or the load devices. Connecting a schottky diode (D1) between the VOUT pin and GND has the effect of preventing damage to them.

TECHNICAL NOTES

PHASE COMPENSATION

In these ICs, phase compensation is made for securing stable operation even if the load current is varied. For this purpose, use a capacitor C2 with 1.0 μ F or more and good ESR (Equivalent Series Resistance).

(Note: If additional ceramic capacitors are connected with parallel to the output pin with an output capacitor for phase compensation, the operation might be unstable. Because of this, test these ICs with as same external components as ones to be used on the PCB).

PCB LAYOUT

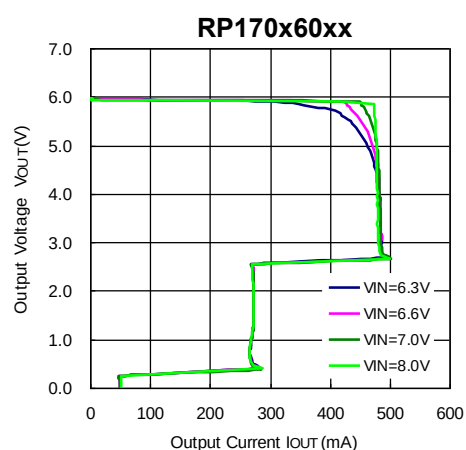
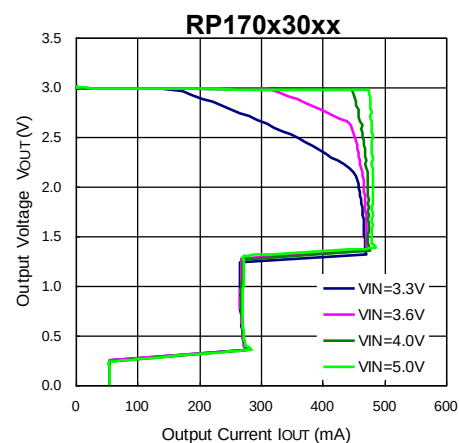
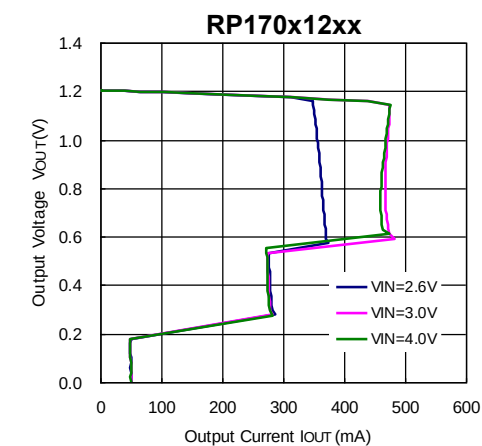
Make V_{DD} and GND lines sufficient. If their impedance is high, noise pickup or unstable operation may result. Connect a capacitor C1 with a capacitance value as much as 1.0 μ F or more between V_{DD} and GND, and as close as possible to the pins.

Set external components, especially the output capacitor C2, as close as possible to the ICs, and make wiring as short as possible.

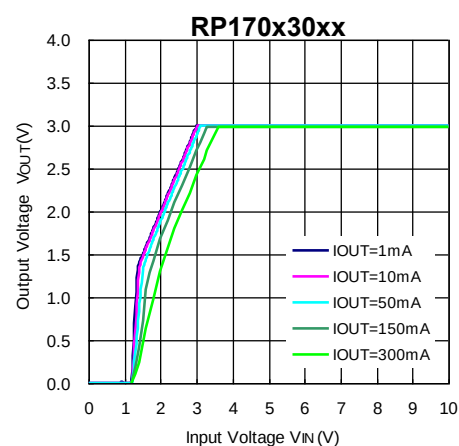
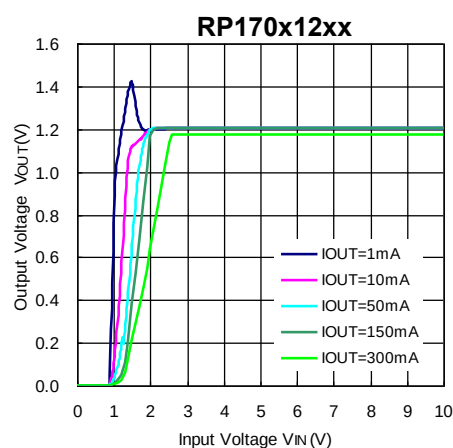
TYPICAL CHARACTERISTICS

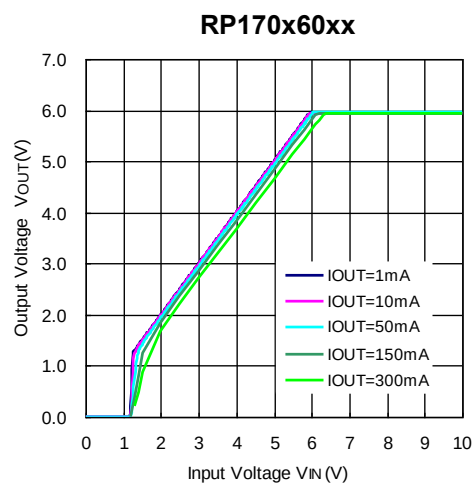
Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

1) Output Voltage vs. Output Current (Ta = 25°C)

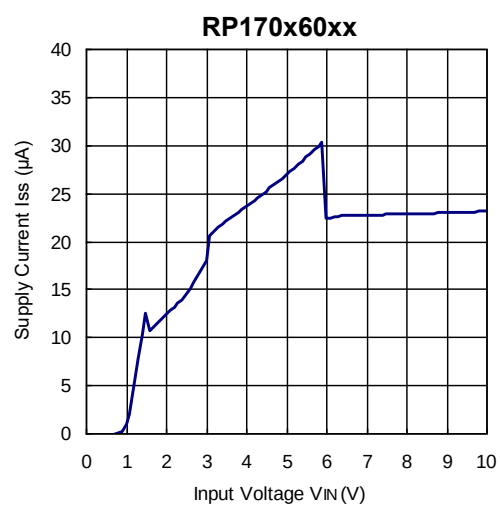
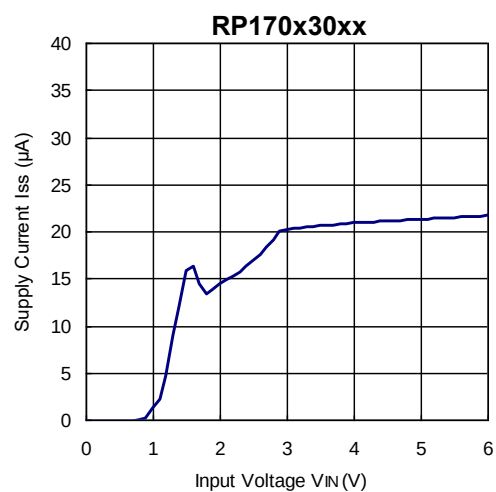
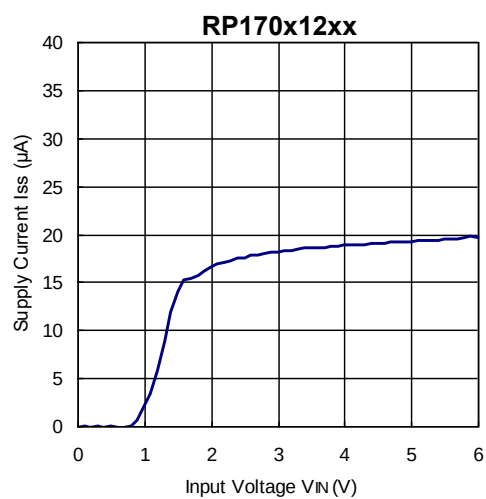


2) Output Voltage vs. Input Voltage (Ta = 25°C)

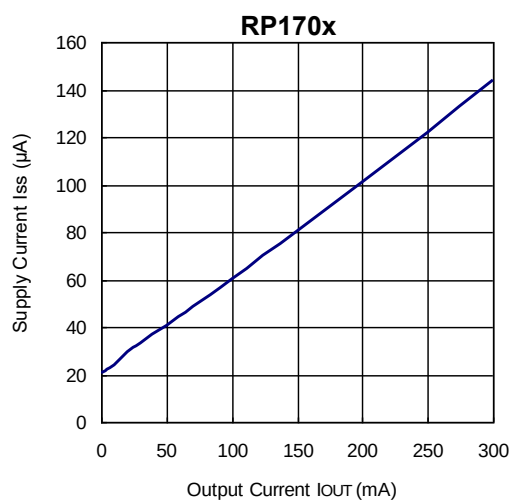




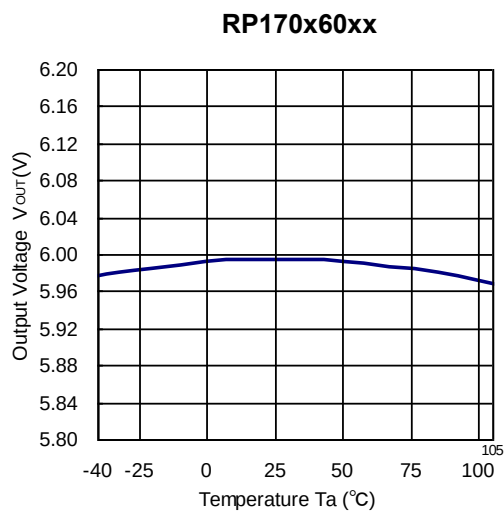
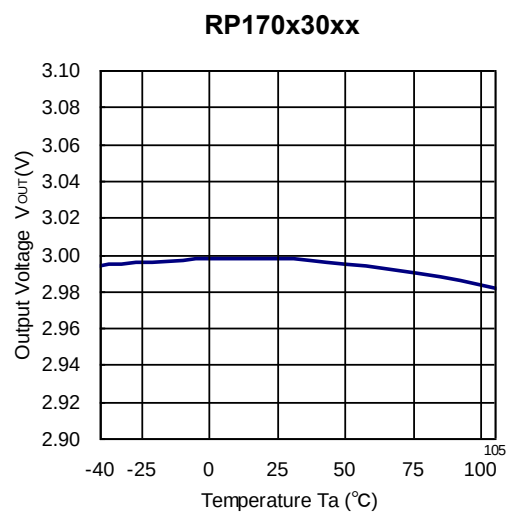
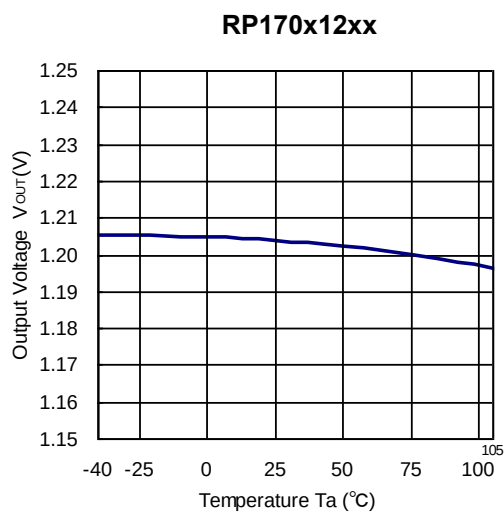
3) Supply Current vs. Input Voltage ($T_a = 25^\circ C$)



4) Supply Current vs. Output Current ($T_a = 25^\circ\text{C}$)

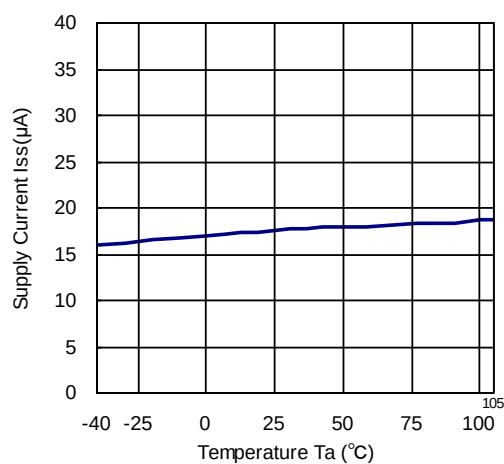


5) Output Voltage vs. Temperature

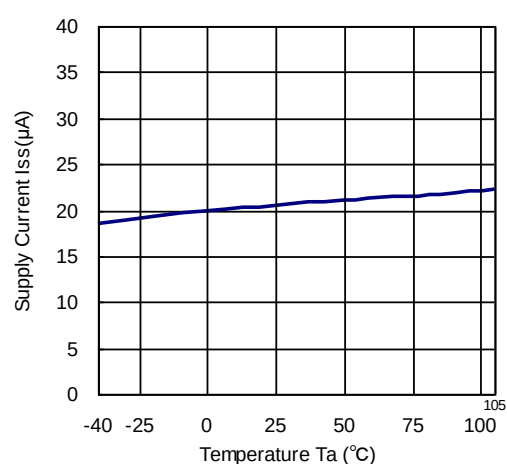


6) Supply Current vs. Temperature

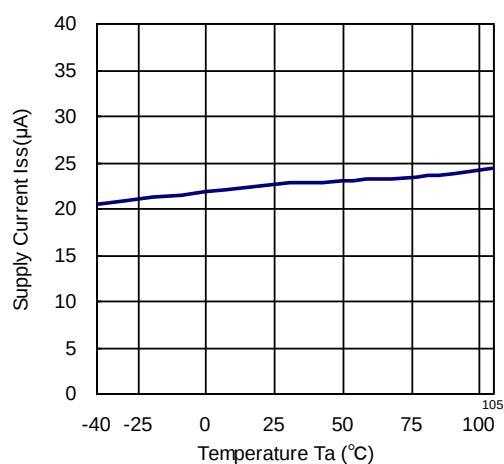
RP170x12xx



RP170x30xx

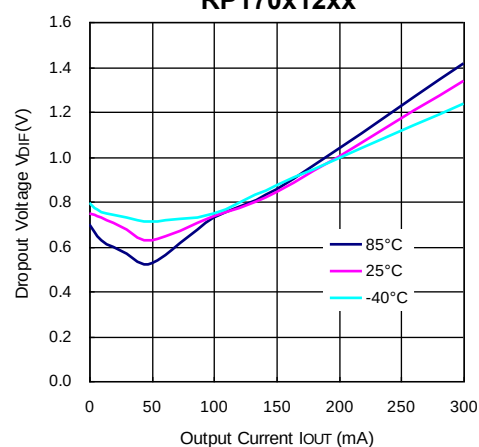


RP170x60xx

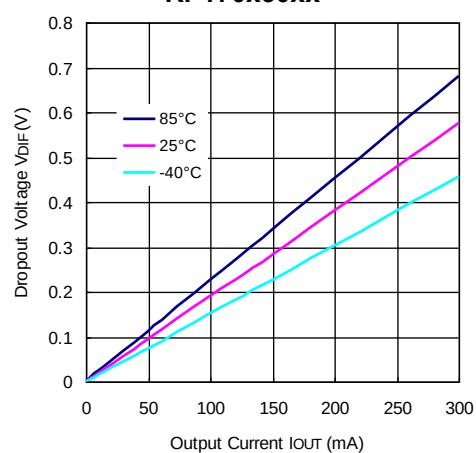


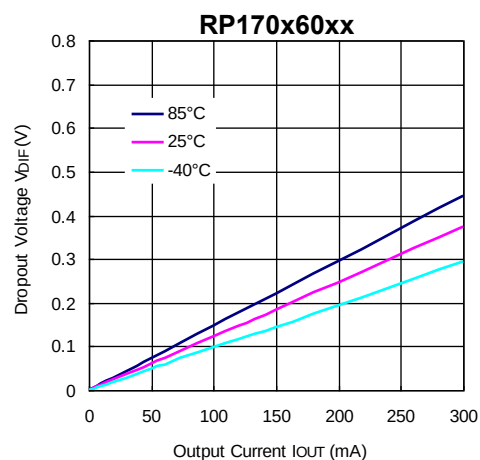
7) Dropout Voltage vs. Output Current

RP170x12xx

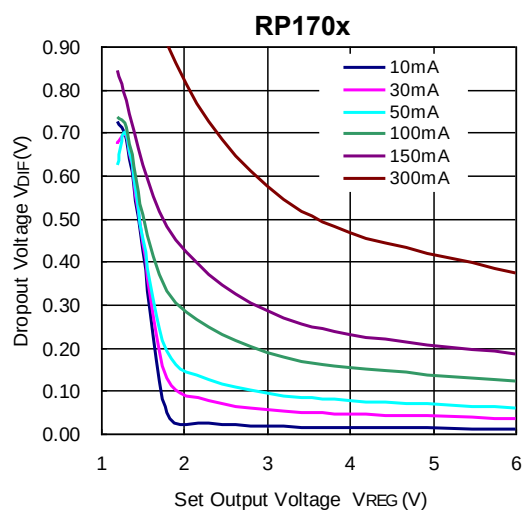


RP170x30xx

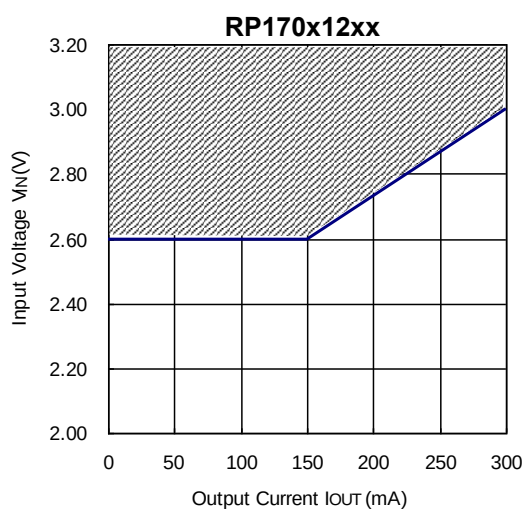




8) Dropout Voltage vs. Set Output Voltage ($T_a = 25^\circ\text{C}$)

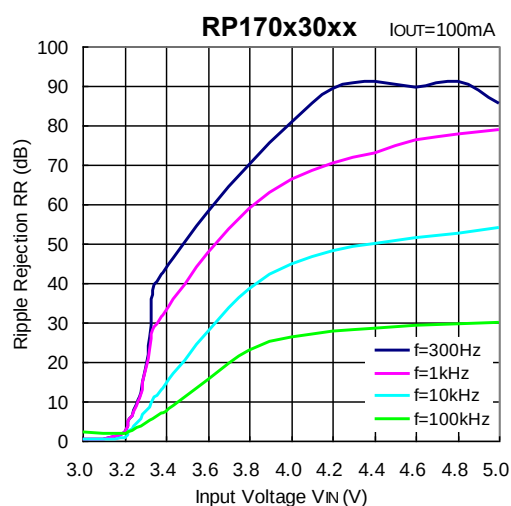
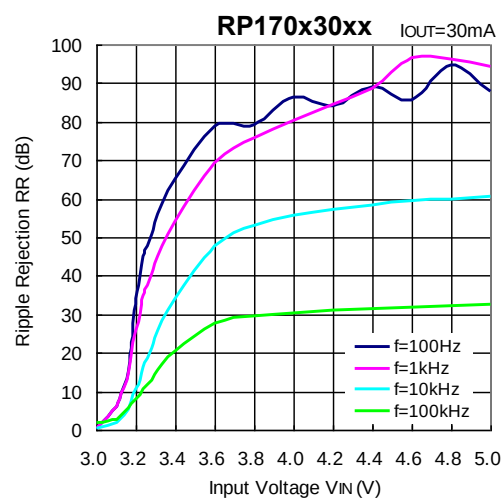
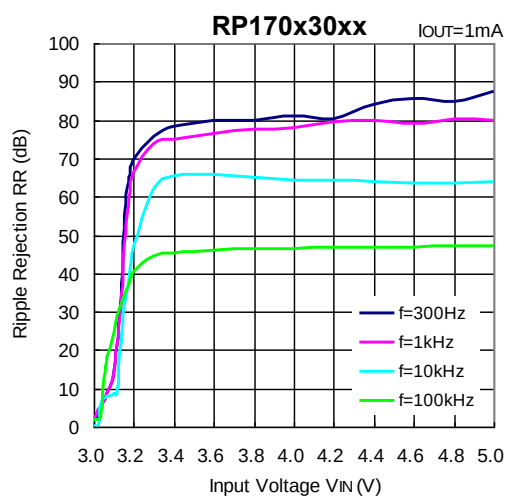


9) Minimum Operating Voltage

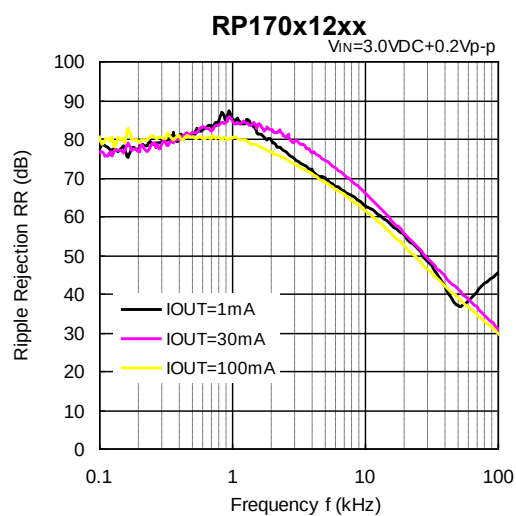
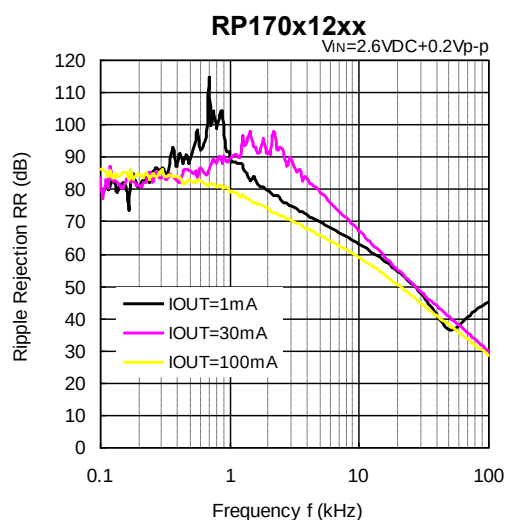


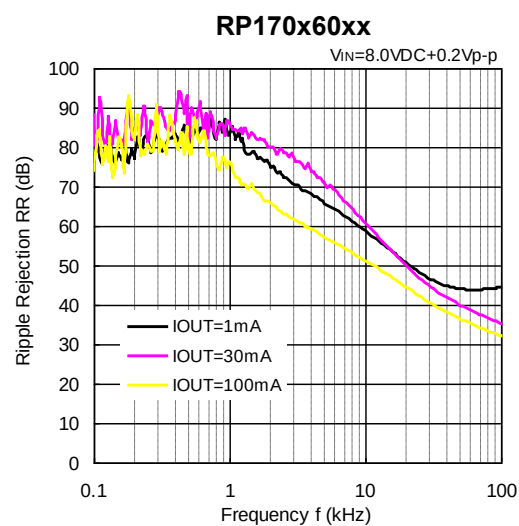
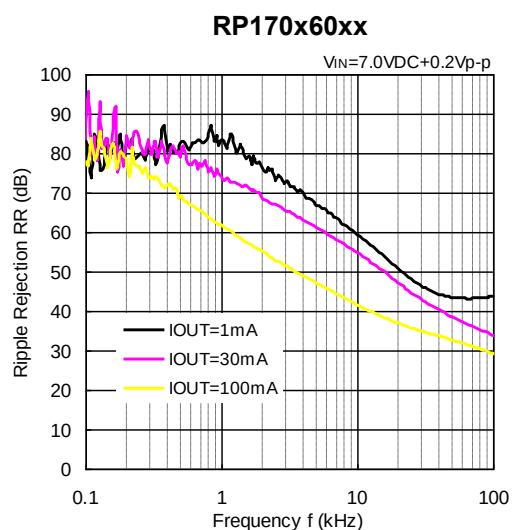
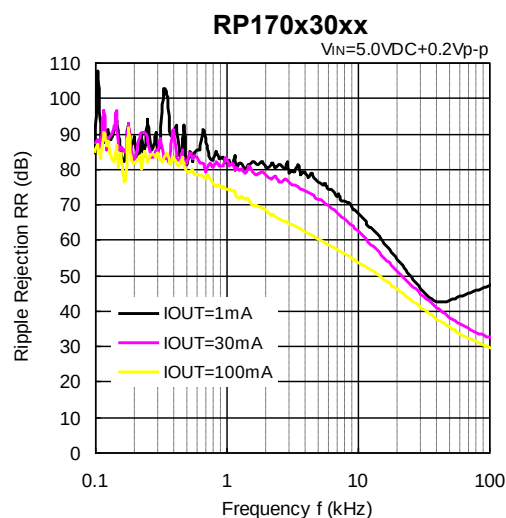
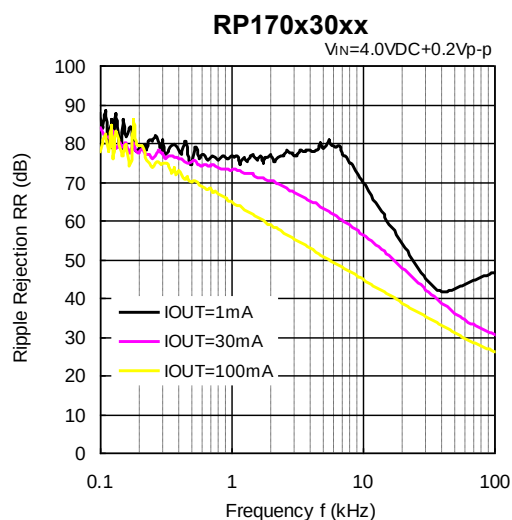
Hatched area is available for 1.2 V output

10) Ripple Rejection vs. Input Bias Voltage (C1 = none, C2 = Ceramic 1.0 μ F, Ripple = 0.2 Vp-p, Ta = 25°C)

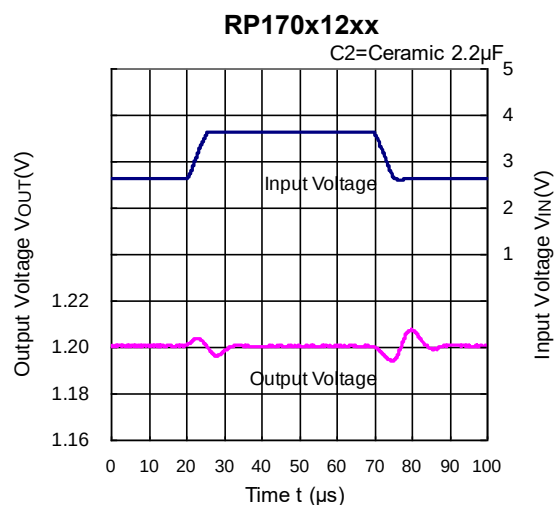
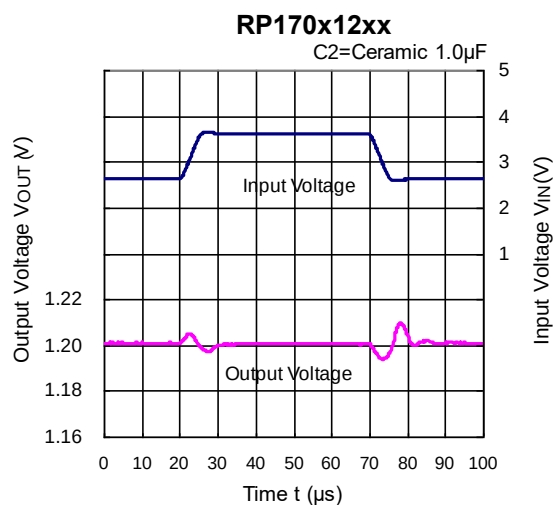


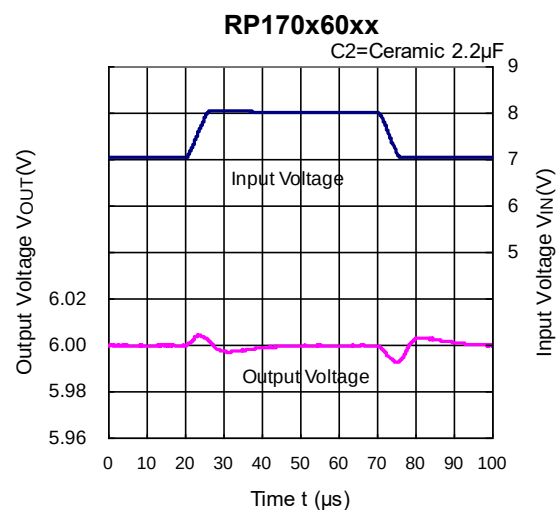
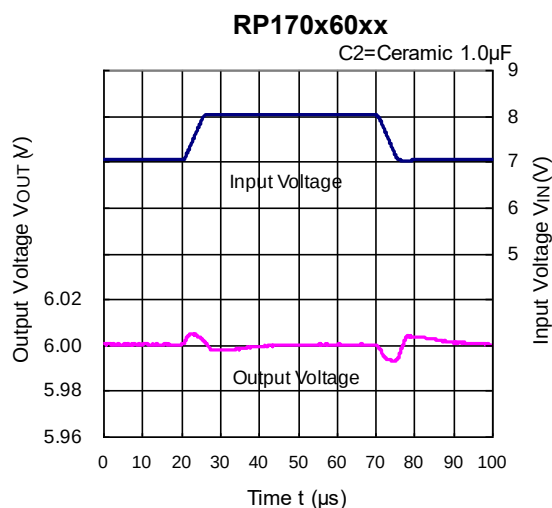
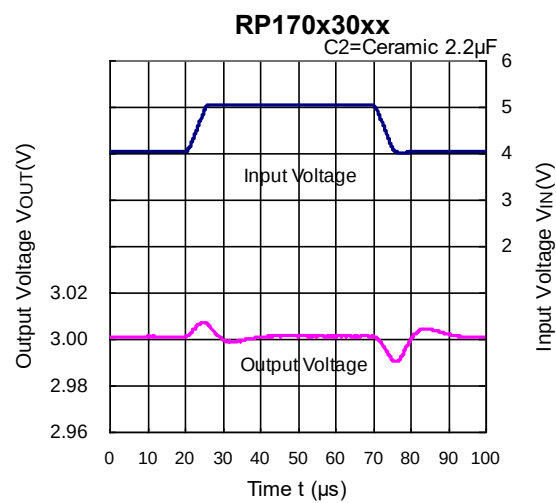
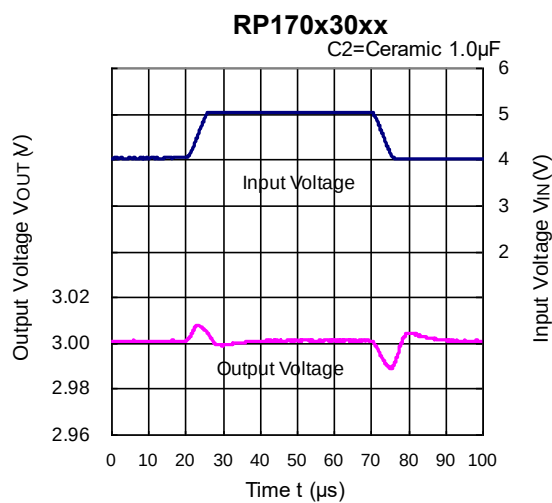
11) Ripple Rejection vs. Frequency (C1 = none, C2 = Ceramic 1.0 μ F, Ta = 25°C)



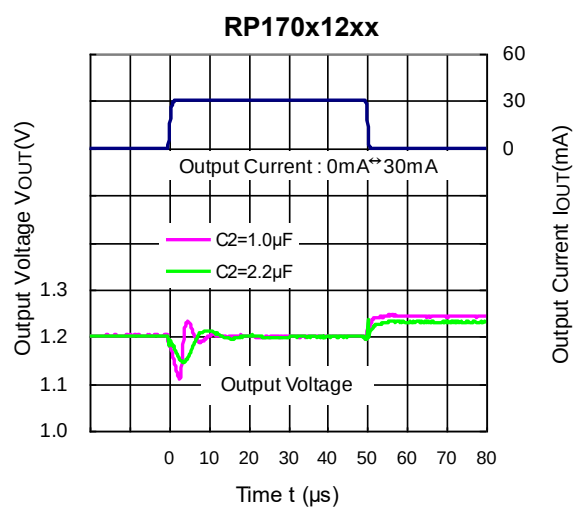
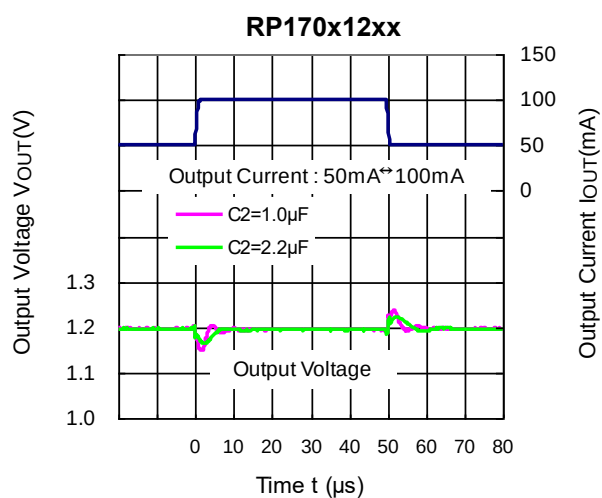


12) Input Transient Response ($C1 = \text{none}$, $I_{OUT} = 30 \text{ mA}$, $t_r = t_f = 5 \mu\text{s}$, $T_a = 25^\circ\text{C}$)

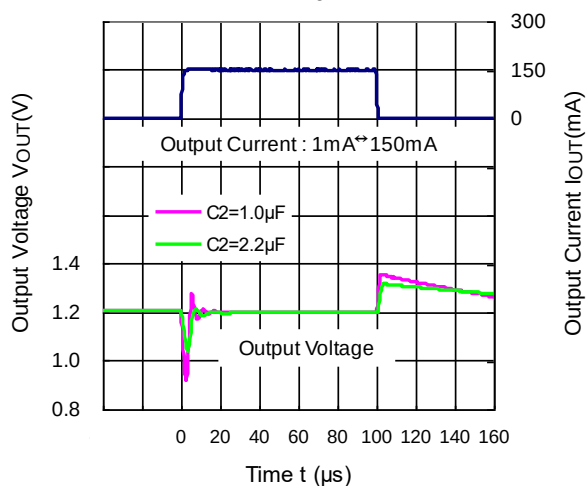




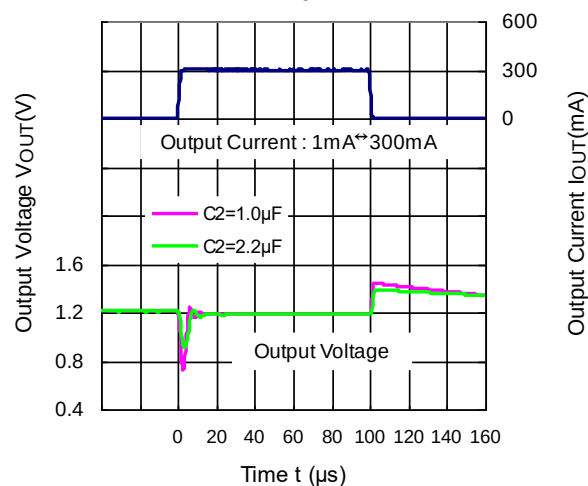
13) Load Transient Response (C1 = Ceramic 1.0 μ F, $t_r = t_f = 500$ ns, $T_a = 25^\circ\text{C}$)



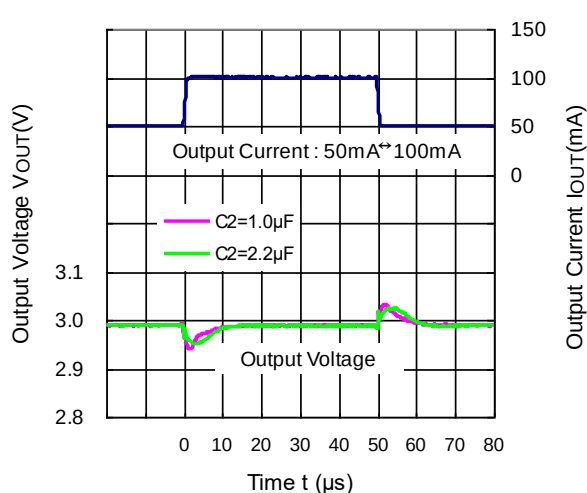
RP170x12xx



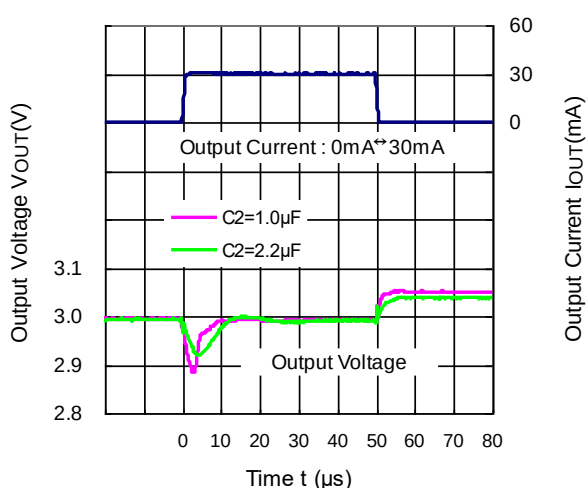
RP170x12xx



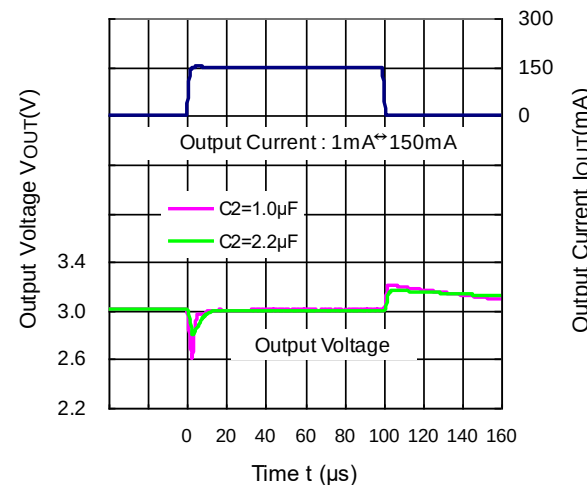
RP170x30xx



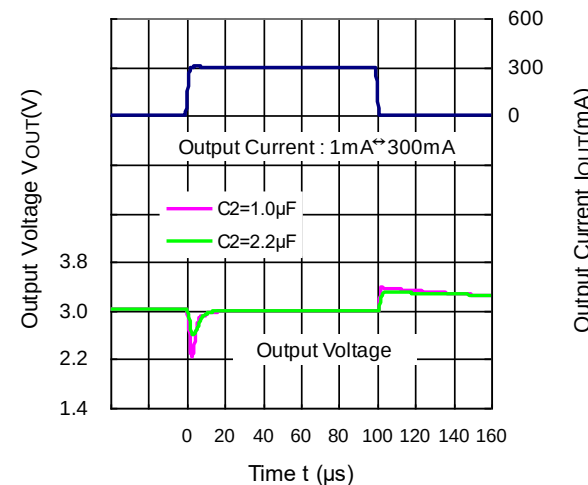
RP170x30xx



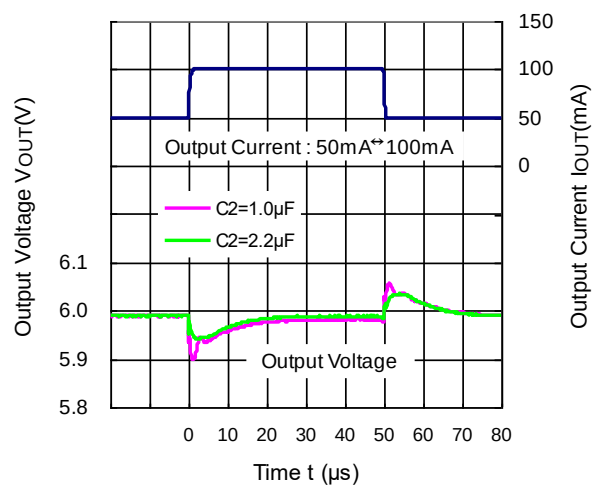
RP170x30xx



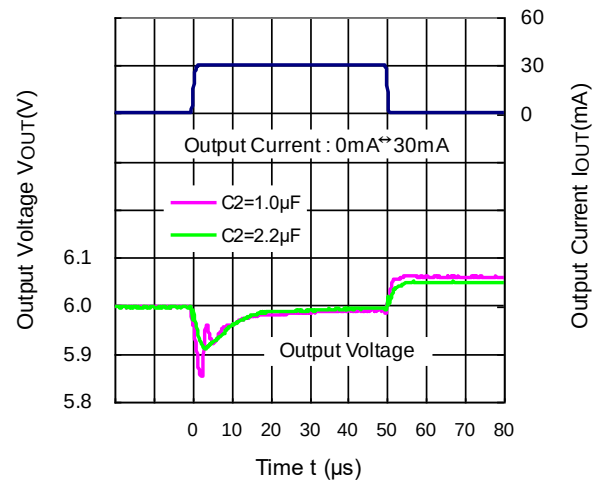
RP170x30xx



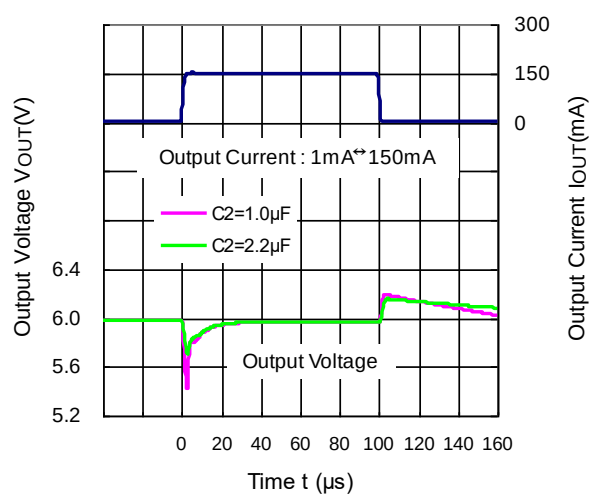
RP170x60xx



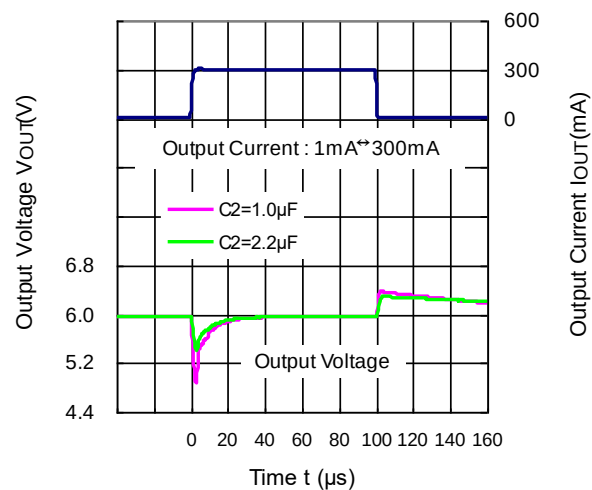
RP170x60xx



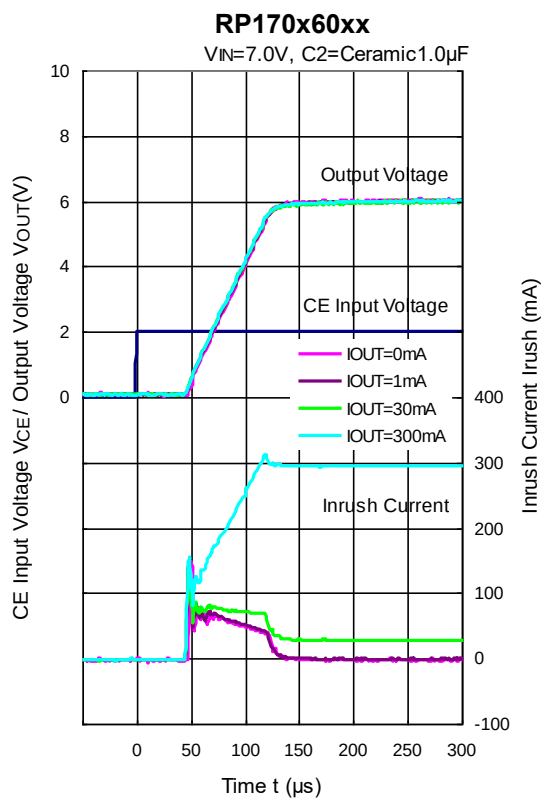
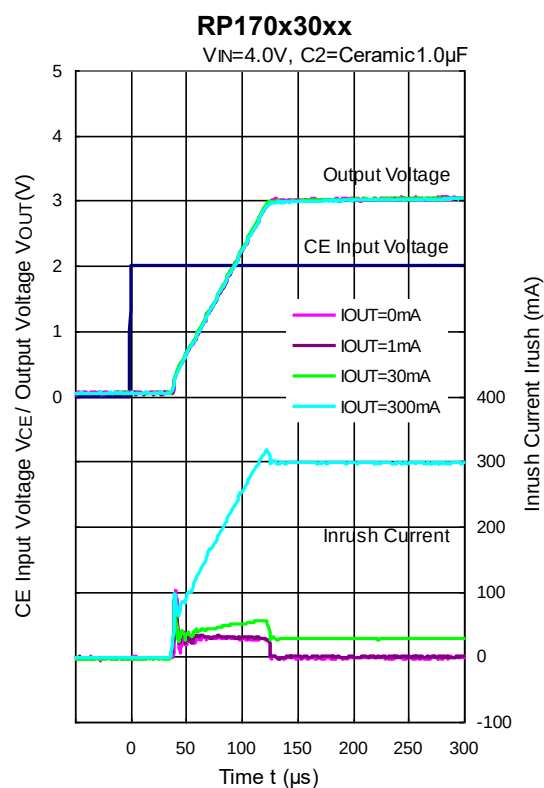
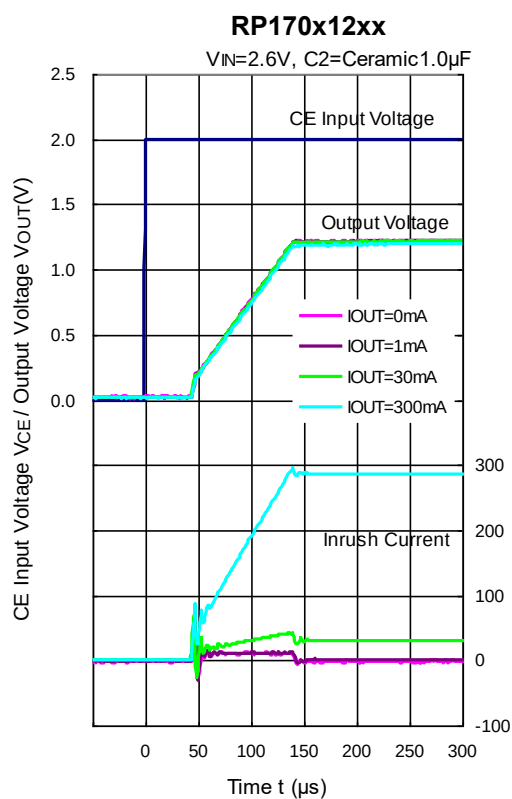
RP170x60xx



RP170x60xx

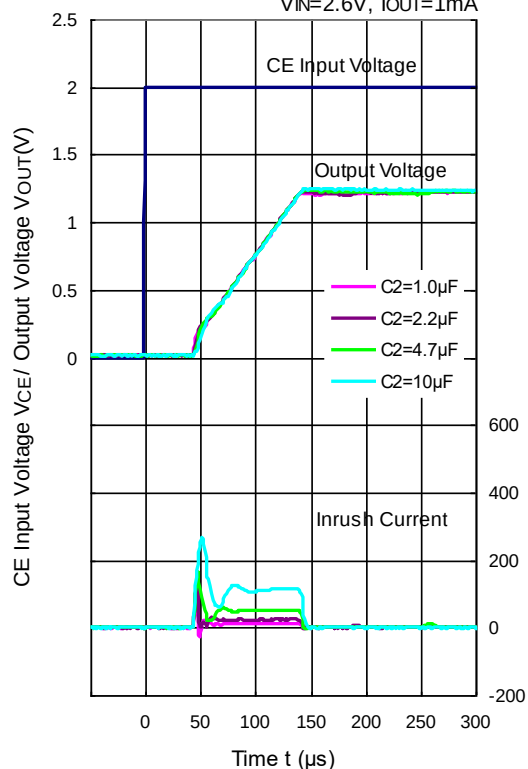


14) Turn On Speed with CE pin (C1 = Ceramic 1.0 μ F, Ta = 25°C)



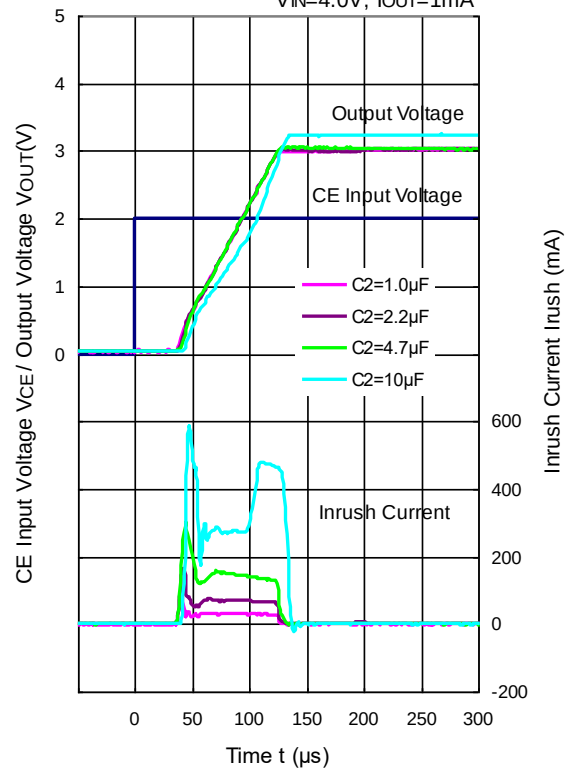
RP170x12xx

V_{IN}=2.6V, I_{OUT}=1mA



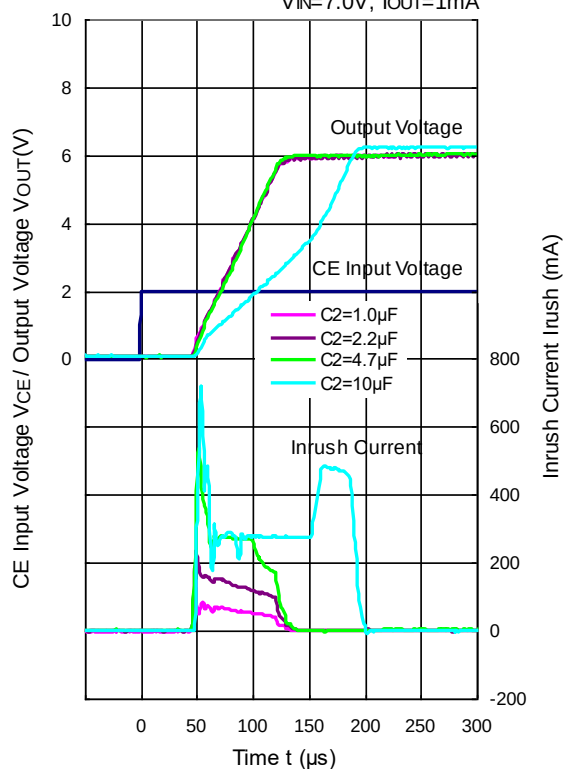
RP170x30xx

V_{IN}=4.0V, I_{OUT}=1mA



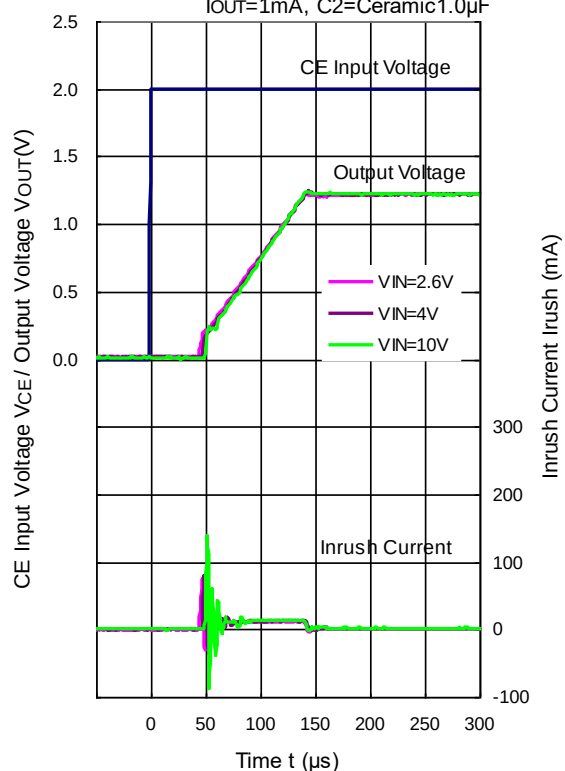
RP170x60xx

V_{IN}=7.0V, I_{OUT}=1mA



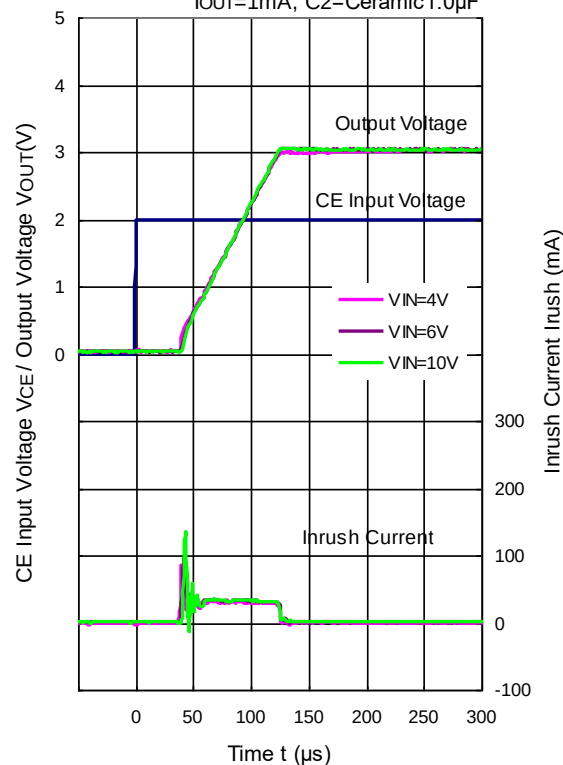
RP170x12xx

I_{OUT}=1mA, C₂=Ceramic1.0μF



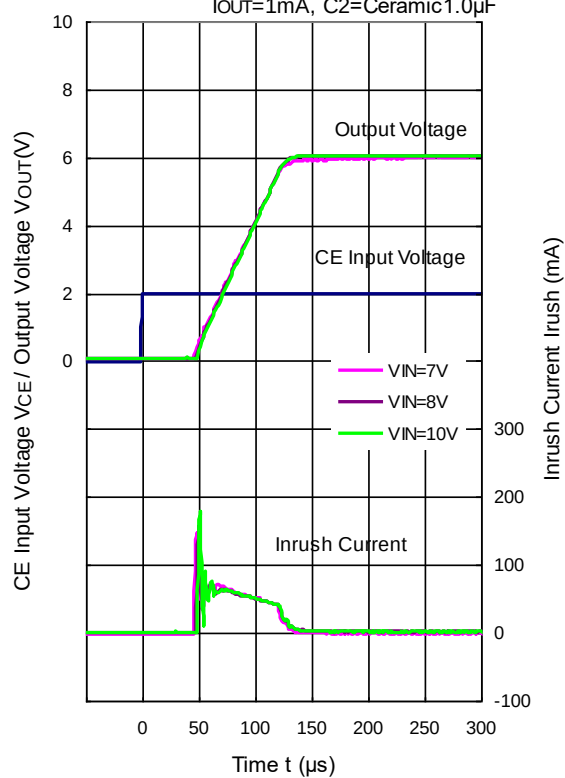
RP170x30xx

I_{OUT}=1mA, C₂=Ceramic1.0μF

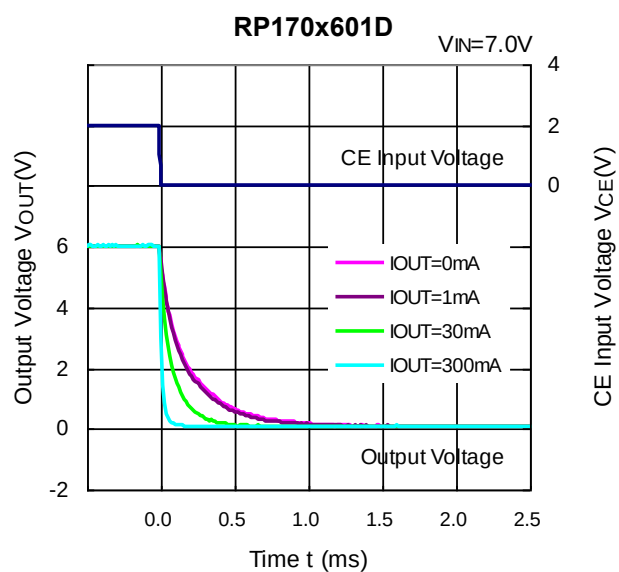
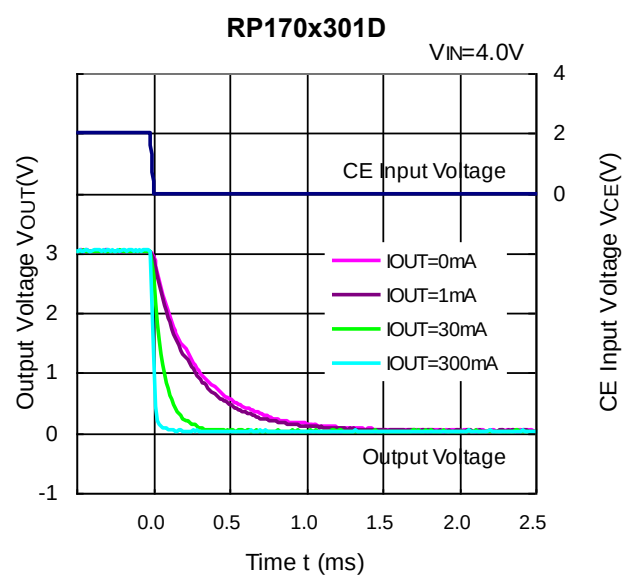
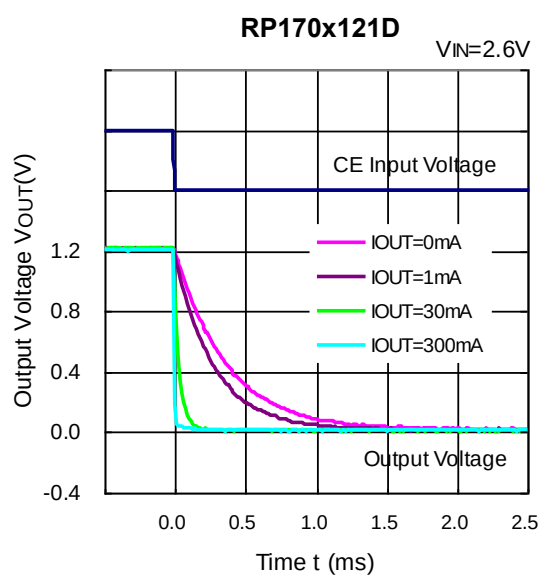


RP170x60xx

I_{OUT}=1mA, C₂=Ceramic1.0μF



15) Turn Off Speed with CE pin (RP170xxx1D) (C1 = Ceramic 1.0 μ F, Ta = 25°C)



ESR vs. Output Current

Ceramic type output capacitor is recommended for this IC; however, the other output capacitors with low ESR also can be used. The relations between I_{OUT} (Output Current) and ESR of an output capacitor are shown below. The conditions when the white noise level is under $40\ \mu\text{V}$ (Avg.) are marked as the hatched area in the graph.

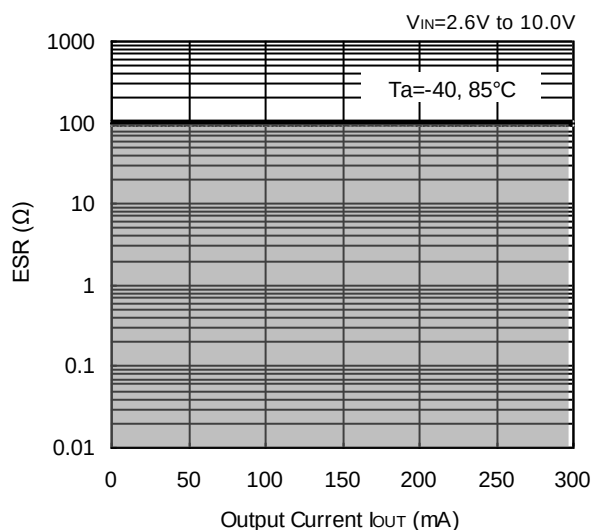
Measurement conditions

Frequency Band : 10 Hz to 2 MHz

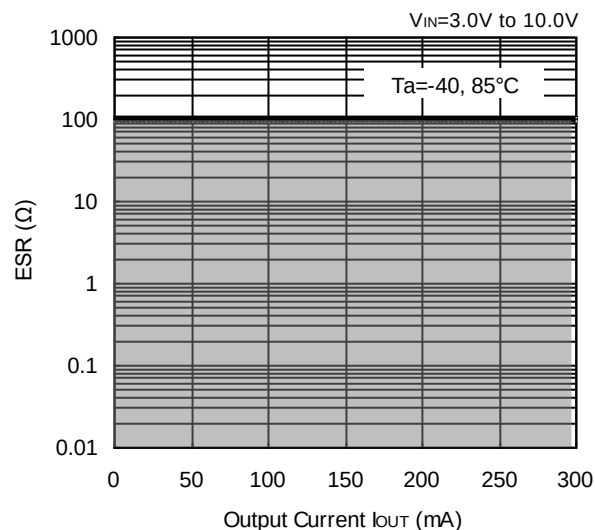
Temperature : -40°C to 85°C

C1, C2 : Ceramic $1.0\ \mu\text{F}$ (Murata GRM155B31A105KE)

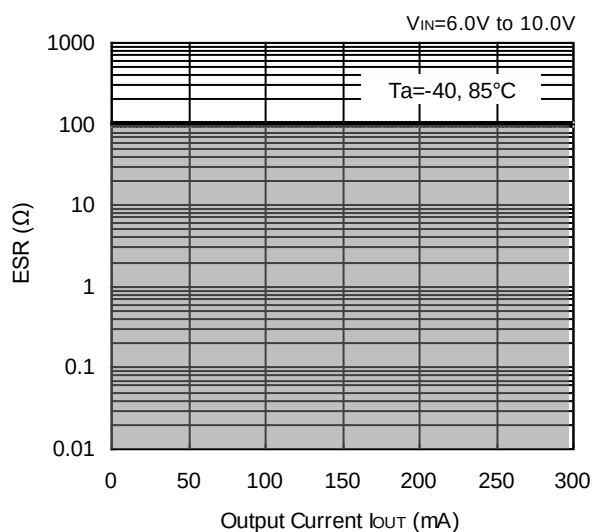
RP170x12xx



RP170x30xx



RP170x60xx



The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

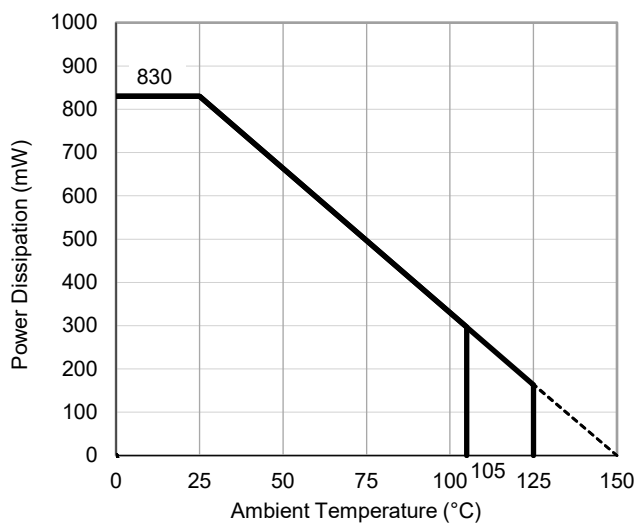
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 7 pcs

Measurement Result

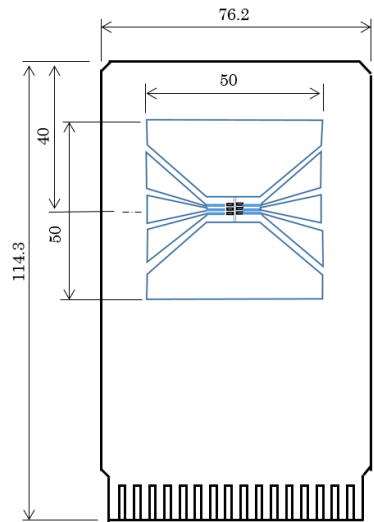
(Ta = 25°C, Tjmax = 150°C)

Item	Measurement Result
Power Dissipation	830 mW
Thermal Resistance (θja)	θja = 150°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 51°C/W

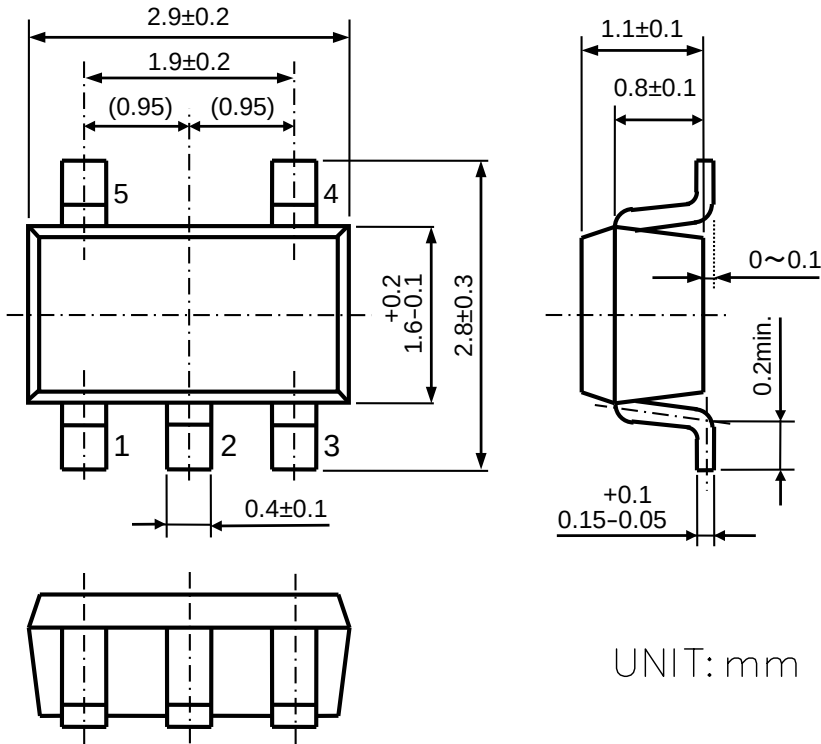
θja: Junction-to-Ambient Thermal Resistance
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



SOT-23-5 Package Dimensions

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

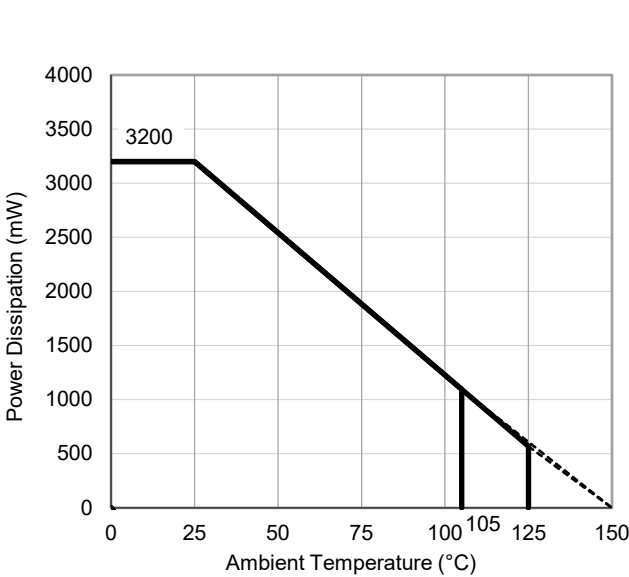
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 13 pcs

Measurement Result

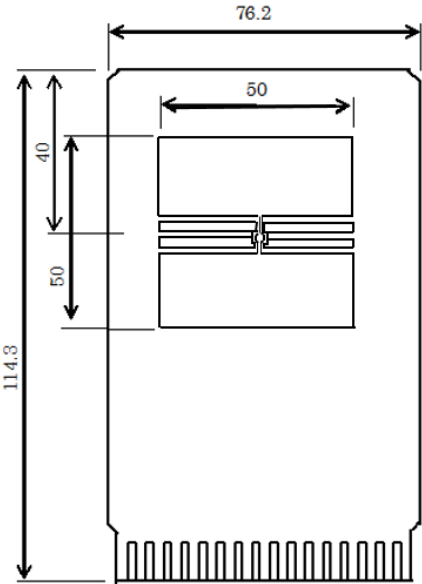
(Ta = 25°C, Tjmax = 150°C)

Item	Measurement Result
Power Dissipation	3200 mW
Thermal Resistance (θja)	θja = 38°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 13°C/W

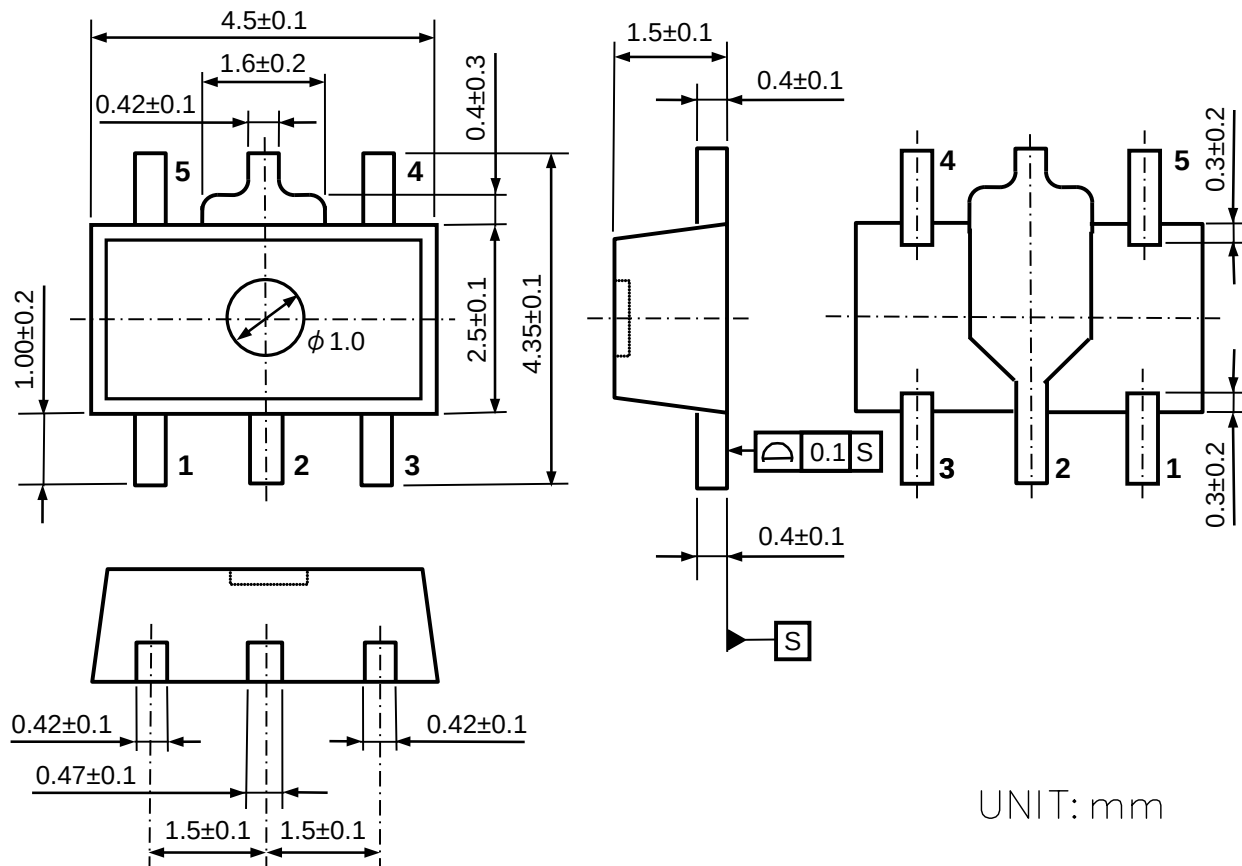
θja: Junction-to-Ambient Thermal Resistance
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



SOT-89-5 Package Dimensions

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 - Traffic control system
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 - 8-2. Quality Warranty Remedies

When it has been proved defective due to manufacturing factors as a result of defect analysis by us, we will either deliver a substitute for the defective product or refund the purchase price of the defective product.

Note that such delivery or refund is sole and exclusive remedies to your company for the defective product.
 - 8-3. Remedies after Quality Warranty Period

With respect to any defect of this product found after the quality warranty period, the defect will be analyzed by us. On the basis of the defect analysis results, the scope and amounts of damage shall be determined by mutual agreement of both parties. Then we will deal with upper limit in Section 8-2. This provision is not intended to limit any legal rights of your company.
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